

ABSTRACT

The present invention provides a conductive adhesive that is applicable as means for forming conductive junction to process for surface mounting of electronic parts for vehicle loading and process for the manufacture of the electronic parts per-se for the purpose of substituting soldering therewith. The conductive adhesive according to the present invention is a conductive adhesive produced by dispersing a conductive medium, such as silver powder, in a binder resin component of a one-component epoxy thermosetting resin which has such a composition that the resin comprises, as essential components, an epoxy resin component composed mainly of an epoxy compound with a polycyclic aromatic ring skeleton, and a cyclic acid anhydride as a curing agent component thereof, and is further added with a coupling agent as an adherence imparting agent therefor.